

## FEATURES AND SPECIFICATIONS

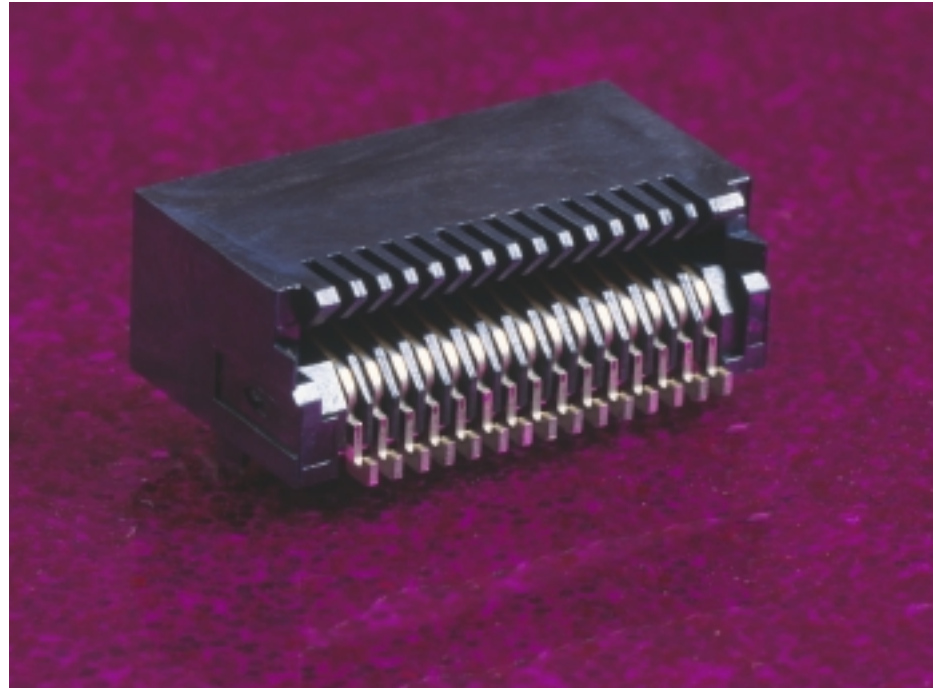


# 0.80mm (.031") Pitch Z-Axis Pluggable Host Connector for 10 Gigabit XFP Modules

Right Angle, SMT, 30-Pin

### Features and Benefits

- 30-pin, 0.80mm (.031") pitch connector with SMT leads for high-speed data transmission
- Coplanarity of solder terminals within 0.10mm (.004") for processing reliability
- Card entry slot accepts 1.0mm (.039") thick integrated circuit board for use with MSA-compliant pluggable modules
- Alignment posts provide stable placement on the PCB during processing
- Standoffs allow easy PCB cleaning after soldering
- Tape-and-reel packaging for SMT robotic placement
- SMT design provides option for connector placement on either side of the PCB
- High-temperature thermoplastic, UL94V-0, for dimensional stability
- Select-gold plated contacts with a choice of plating thicknesses for optimizing cost and performance



The 30-pin Z-Axis Pluggable host connector enables the use of emerging gigabit-speed hot-pluggable transceiver modules for horizontal front-panel access. It conforms to the host-board layout as defined in the 10 Gigabit Small Form Factor Pluggable (XFP) Multi-source Agreement (MSA) for 10-Gigabit data rates. Molex is referenced as an approved source in the MSA.

The XFP MSA provides a specification for the pluggable module, cage, and host connector to convert serial electrical signals to external serial optical or electrical signals. XFP operates with SONET OC-192, 10 Gigabit Fibre Channel, and 10 Gigabit Ethernet links with the same form-factor module, for an economical 10-Gigabit solution. Module pluggability increases configuration flexibility by providing postponement manufacturing capability and a pay-as-you-populate cost structure for the end-user after installation.

The 30-pin host connector features a compact, high bandwidth interface to support the XFI ("Ziffy") 10Gbps serial electrical interface specification. The connector is typically used in conjunction with an XFP cage, flange and EMI gasket assembly, along with a heat sink and attachment clip, to attach an optical LC duplex or electrical XFP transceiver module to the host board.

The XFP MSA group brings together leading networking, system, semiconductor and connector companies, including Molex, from both the telecommunications and datacommunications markets.

The Z-Axis Pluggable host connectors are also available in other circuit sizes for use with Small Form-factor Pluggable (SFP), XENPAK, and other 10-Gigabit pluggable transceivers.

## APPLICATIONS

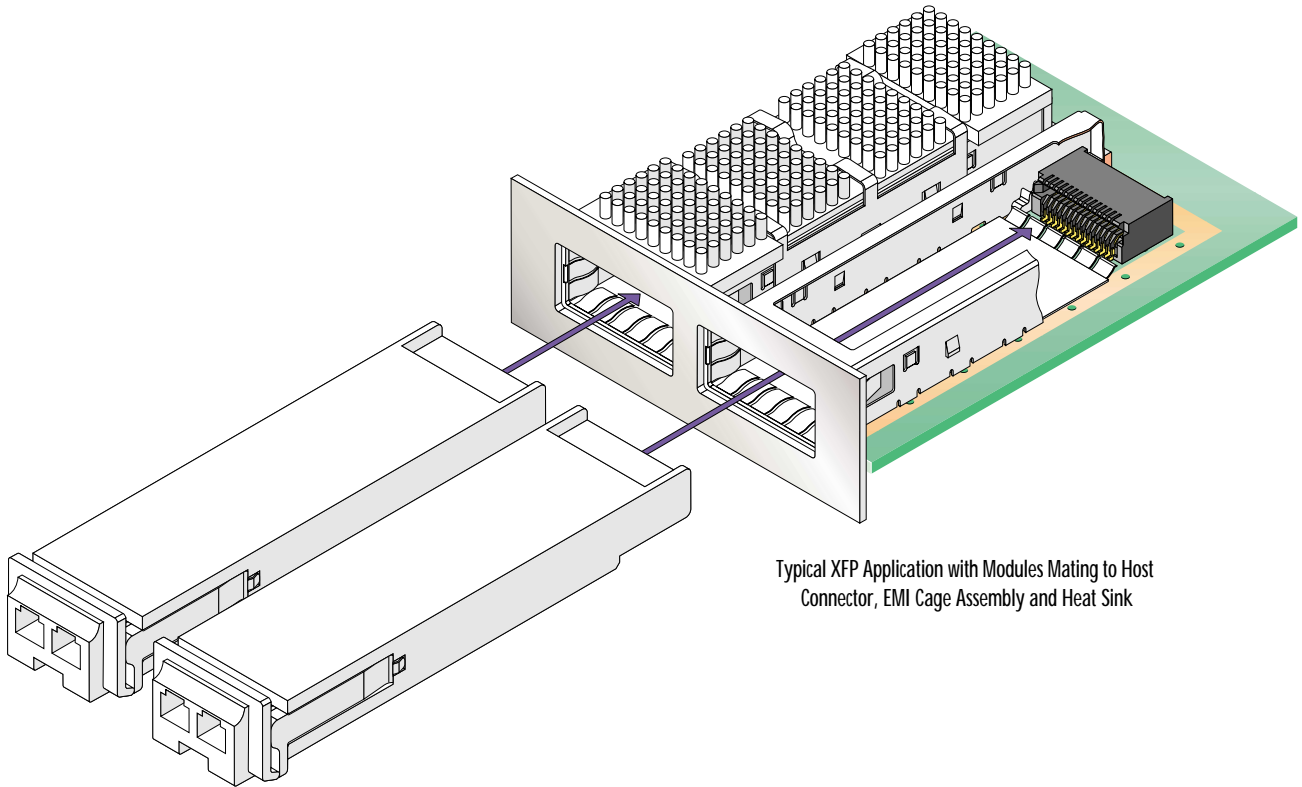
The 30-pin host connector attaches 10-Gigabit XFP pluggable transceivers in a horizontal Z-axis to the host PCB for use in various data networking equipment:

- Switches
- Routers
- Servers
- Storage devices



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## Right Angle, SMT, 30-Pin



Typical XFP Application with Modules Mating to Host Connector, EMI Cage Assembly and Heat Sink

## ORDERING INFORMATION

30-Pin Host Connector Order Number	Select Gold Plating Thickness
74441-0007	0.38mm (15 $\mu$ )
74441-0017	0.76mm (30 $\mu$ )

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